

NPL Search for paper no. 0705


[Home](#) | [Login](#) | [Logout](#) | [Access Information](#) | [Alerts](#)

Welcome United States Patent and Trademark Office

Search Results

BROWSE

SEARCH

IEEE XPLORE GUIDE

Results for "(copper<in>metadata) <and> (oxide<in>metadata) <and> (aluminum<in>g..."

Your search matched 73 of 1189536 documents.

A maximum of 100 results are displayed, 25 to a page, sorted by Relevance in Descending order.

» [View Session History](#)» [New Search](#)

» Key

IEEE JNL IEEE Journal or Magazine

IEE JNL IEE Journal or Magazine

IEEE CNF IEEE Conference Proceeding

IEE CNF IEE Conference Proceeding

IEEE STD IEEE Standard

Modify Search

(copper<in>metadata) <and> (oxide<in>metadata) <and> (aluminum<in>metadata)

☐ Check to search only within this results setDisplay Format: ☒ Citation ☐ Citation & Abstract

Select Article Information

View: 1-

- ☐ 1. **Comparison of various substrate technologies under steady state and transient**
Larson, S.E.; Slaby, J.;
Thermal and Thermomechanical Phenomena in Electronic Systems, 2004. ITherm '04.
Intersociety Conference on
Volume 2, 1-4 June 2004 Page(s):648 - 654 Vol.2
[AbstractPlus](#) | Full Text: [PDF](#)(461 KB) IEEE CNF
- ☐ 2. **Comparison between gate oxide degradation induced by copper dual damascene**
conventional aluminum processes
Poiroux, T.; Heitzmann, M.; Morand, Y.; Berruyer, P.; Turban, G.; Reimbold, G.;
Plasma Process-Induced Damage, 1999 4th International Symposium on
9-11 May 1999 Page(s):177 - 180
[AbstractPlus](#) | Full Text: [PDF](#)(184 KB) IEEE CNF
- ☐ 3. **Bonding mechanism between aluminum nitride substrate and Ag-Cu-Ti solder**
Kurihara, Y.; Takahashi, S.; Ogihara, S.; Kurosu, T.;
Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [see also
Components, Packaging, and Manufacturing Technology, Part A, B, C]
Volume 15, Issue 3, June 1992 Page(s):361 - 368
[AbstractPlus](#) | Full Text: [PDF](#)(1056 KB) IEEE JNL
- ☐ 4. **Behavior of aluminum nitride ceramic surfaces under hydrothermal oxidation tre**
Suryanarayana, D.; Matienzo, L.J.; Spencer, D.F.;
Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [see also
Components, Packaging, and Manufacturing Technology, Part A, B, C]
Volume 12, Issue 4, Dec. 1989 Page(s):566 - 570
[AbstractPlus](#) | Full Text: [PDF](#)(600 KB) IEEE JNL
- ☐ 5. **Etch rates for micromachining processing-Part II**
Williams, K.R.; Gupta, K.; Wasilik, M.;
Microelectromechanical Systems, Journal of
Volume 12, Issue 6, Dec. 2003 Page(s):761 - 778
[AbstractPlus](#) | [References](#) | Full Text: [PDF](#)(1047 KB) IEEE JNL
- ☐ 6. **A transmission electron microscopy study of ultrasonic wire bonding**
Krzanowski, J.E.;
Electronic Components Conference, 1989. Proceedings., 39th

22-24 May 1989 Page(s):450 - 455

[AbstractPlus](#) | Full Text: [PDF](#)(668 KB) IEEE CNF

- ☐ **7. Corrosion susceptibility of thin-film metallizations**
Griffin, A.J., Jr.; Brotzen, F.R.; McPherson, J.W.; Dunn, C.F.;
Reliability Physics Symposium 1992. 30th Annual Proceedings., International
31 March-2 April 1992 Page(s):239 - 246
[AbstractPlus](#) | Full Text: [PDF](#)(712 KB) IEEE CNF
- ☐ **8. Enhanced EM endurance of TiN/AlCu/TiN_x interconnection**
Jeong Soo Byun; Jun Ki Kim; Kwan Goo Rha; Woo Shik Kim;
Integrated Reliability Workshop, 1994. Final Report., 1994 International
16-19 Oct. 1994 Page(s):144
[AbstractPlus](#) | Full Text: [PDF](#)(60 KB) IEEE CNF
- ☐ **9. Reactive magnetron sputtering of transparent and conductive zinc oxide films de
rates onto CIS/CIGS photovoltaic devices**
Gillespie, T.J.; Miles, W.A.; del Cueto, J.A.;
Photovoltaic Specialists Conference, 1997., Conference Record of the Twenty-Sixth IE
29 Sept.-3 Oct. 1997 Page(s):487 - 490
[AbstractPlus](#) | Full Text: [PDF](#)(284 KB) IEEE CNF
- ☐ **10. Probe contact resistance variations during elevated temperature wafer test**
Broz, J.J.; Rincon, R.M.;
Test Conference, 1999. Proceedings. International
28-30 Sept. 1999 Page(s):396 - 405
[AbstractPlus](#) | Full Text: [PDF](#)(896 KB) IEEE CNF
- ☐ **11. A comparison of via overetch variations between conventional Al-W and dual-int.
integrations**
Smith, B.; Blackley, S.; Carter, R.; Chheda, S.; Crabtree, P.; Farber, D.; Gall, M.; Islam
King, C.; Menke, D.; Nelson, R.; Pressley, L.; Smith, D.; Sparks, T.; Stephens, T.; Trav
Venkatesan, S.;
Interconnect Technology, 1999. IEEE International Conference
24-26 May 1999 Page(s):106 - 108
[AbstractPlus](#) | Full Text: [PDF](#)(392 KB) IEEE CNF
- ☐ **12. Characterization of extrusion formation during high temperature anneal**
Kelsey-Wynne, J.; Chen, F.; Furukawa, J.; Sullivan, T.;
Integrated Reliability Workshop Final Report, 2000 IEEE International
23-26 Oct. 2000 Page(s):161 - 164
[AbstractPlus](#) | Full Text: [PDF](#)(412 KB) IEEE CNF
- ☐ **13. Standard free determination of trace metals in semiconductor chemicals by ICP-**
Lin, Y.P.; Liu, S.H.; Lai, W.S.; Chen, S.L.;
Semiconductor Manufacturing Technology Workshop, 2002
10-11 Dec. 2002 Page(s):172 - 175
[AbstractPlus](#) | Full Text: [PDF](#)(305 KB) IEEE CNF
- ☐ **14. Comparison between beryllium-copper and tungsten high frequency air coplanar**
Carbonero, J.-L.; Morin, G.; Cabon, B.;
Microwave Theory and Techniques, IEEE Transactions on
Volume 43, Issue 12, Dec. 1995 Page(s):2786 - 2793
[AbstractPlus](#) | Full Text: [PDF](#)(832 KB) IEEE JNL
- ☐ **15. Electromigration performance of electroless plated copper/Pd-silicide metallizati**
Tao, J.; Cheung, N.W.; Hu, C.; Kang, H.-K.; Wong, S.S.;

Electron Device Letters, IEEE
Volume 13, Issue 8, Aug. 1992 Page(s):433 - 435
[AbstractPlus](#) | Full Text: [PDF](#)(216 KB) IEEE JNL

- ☐ **16. A transmission electron microscopy study of ultrasonic wire bonding**
Krzanowski, J.E.;
Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [see also Components, Packaging, and Manufacturing Technology, Part A, B, C]
Volume 13, Issue 1, March 1990 Page(s):176 - 181
[AbstractPlus](#) | Full Text: [PDF](#)(732 KB) IEEE JNL
- ☐ **17. Fretting damage in tin-plated aluminum and copper connectors**
Braunovic, M.;
Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [see also Components, Packaging, and Manufacturing Technology, Part A, B, C]
Volume 12, Issue 2, June 1989 Page(s):215 - 223
[AbstractPlus](#) | Full Text: [PDF](#)(976 KB) IEEE JNL
- ☐ **18. Mechanical FEM Simulation of bonding process on Cu lowK wafers**
Degryse, D.; Vandevelde, B.; Beyne, E.;
Components and Packaging Technologies, IEEE Transactions on [see also Component and Manufacturing Technology, Part A: Packaging Technologies, IEEE Transactions on
Volume 27, Issue 4, Dec. 2004 Page(s):643 - 650
[AbstractPlus](#) | Full Text: [PDF](#)(792 KB) IEEE JNL
- ☐ **19. Top-emitting OLED using praseodymium oxide coated platinum as hole injectors**
Chengfeng Qiu; Huajun Peng; Haiying Chen; Zhiliang Xie; Man Wong; Hoi Sing Kwok;
Electron Devices, IEEE Transactions on
Volume 51, Issue 7, July 2004 Page(s):1207 - 1210
[AbstractPlus](#) | [References](#) | Full Text: [PDF](#)(176 KB) IEEE JNL
- ☐ **20. Three-directional analysis of thermally-induced strains for Nb/sub 3/Sn and oxide superconductors**
Murase, S.; Okamoto, H.; Wakasa, T.; Tsukii, T.; Shimamoto, S.;
Applied Superconductivity, IEEE Transactions on
Volume 13, Issue 2, June 2003 Page(s):3386 - 3389
[AbstractPlus](#) | [References](#) | Full Text: [PDF](#)(349 KB) IEEE JNL
- ☐ **21. Effect of underlayer microstructure on the exchange coupling of Mumetal-Al oxide**
Young-woo Lee; Lee, T.H.; Kim, C.G.; Kim, C.O.; Yoon, T.S.;
Magnetics, IEEE Transactions on
Volume 38, Issue 5, Sept. 2002 Page(s):2788 - 2790
[AbstractPlus](#) | [References](#) | Full Text: [PDF](#)(201 KB) IEEE JNL
- ☐ **22. Active circuits under wire bonding I/O pads in 0.13 μm eight-level Cu metal, FSG metal dielectric CMOS technology**
Kuo-Yu Chou; Ming-Jer Chen;
Electron Device Letters, IEEE
Volume 22, Issue 10, Oct. 2001 Page(s):466 - 468
[AbstractPlus](#) | [References](#) | Full Text: [PDF](#)(95 KB) IEEE JNL
- ☐ **23. The impact of interconnection and dielectric materials on the time delay of scale systems**
Nikolic, K.; Berzon, D.; Forshaw, M.;
Electron Devices, IEEE Transactions on
Volume 48, Issue 6, June 2001 Page(s):1121 - 1126
[AbstractPlus](#) | [References](#) | Full Text: [PDF](#)(156 KB) IEEE JNL

- ☐ **24. Non-magnetic substrates for low cost YBCO coated conductors**
Thieme, C.L.H.; Annavarapu, S.; Zhang, W.; Prunier, V.; Fritzscheier, L.; Li, Q.; Schoop, M.W.; Gopal, M.; Foltyn, S.R.; Holesinger, T.;
Applied Superconductivity, IEEE Transactions on
Volume 11, Issue 1, March 2001 Page(s):3329 - 3332
[AbstractPlus](#) | [References](#) | Full Text: [PDF](#)(392 KB) IEEE JNL
- ☐ **25. Design and testing of a kinematic package supporting a 32×32 array of GaAs MQ flip-chip bonded to a CMOS chip**
Ayliffe, M.H.; Rolston, D.R.; Chuah, A.E.L.; Bernier, E.; Michael, F.S.J.; Kabal, D.; Kirk, Lightwave Technology, Journal of
Volume 19, Issue 10, Oct. 2001 Page(s):1543 - 1559
[AbstractPlus](#) | [References](#) | Full Text: [PDF](#)(400 KB) IEEE JNL

[View Selected Items](#)

View: 1-

[Help](#) [Contact Us](#) [Privacy & :](#)

© Copyright 2005 IEEE –

Indexed by
 Inspec

[Home](#) | [Login](#) | [Logout](#) | [Access Information](#) | [Alerts](#) |

Welcome United States Patent and Trademark Office

[Search Results](#)[BROWSE](#)[SEARCH](#)[IEEE XPLORE GUIDE](#)

Results for "(alcuo<in>metadata) <and> (pad<in>metadata)"



Your search matched 0 of 1189536 documents.

A maximum of 100 results are displayed, 25 to a page, sorted by Relevance in Descending order.

[» View Session History](#)[» New Search](#)[» Key](#)

IEEE JNL IEEE Journal or Magazine

IEE JNL IEE Journal or Magazine

IEEE CNF IEEE Conference Proceeding

IEE CNF IEE Conference Proceeding

IEEE STD IEEE Standard

Modify Search

☐ Check to search only within this results setDisplay Format: ☒ Citation ☐ Citation & Abstract

No results were found.

Please edit your search criteria and try again. Refer to the Help pages if you need assistance revisir

[Help](#) [Contact Us](#) [Privacy & :'](#)

© Copyright 2005 IEEE -

Indexed by
 Inspec

[Home](#) | [Login](#) | [Logout](#) | [Access Information](#) | [Alerts](#) |

Welcome United States Patent and Trademark Office

[Search Results](#)[BROWSE](#)[SEARCH](#)[IEEE XPLORE GUIDE](#)

Results for "(aluminum copper oxide<in>metadata) <and> (pad<in>metadata)"



Your search matched 0 of 1189536 documents.

A maximum of 100 results are displayed, 25 to a page, sorted by Relevance in Descending order.

[» View Session History](#)[» New Search](#)[» Key](#)

IEEE JNL IEEE Journal or Magazine

IEE JNL IEE Journal or Magazine

IEEE CNF IEEE Conference Proceeding

IEE CNF IEE Conference Proceeding

IEEE STD IEEE Standard

Modify Search

☐ Check to search only within this results setDisplay Format: ☒ Citation ☐ Citation & Abstract

No results were found.

Please edit your search criteria and try again. Refer to the Help pages if you need assistance revisir

[Help](#) [Contact Us](#) [Privacy & :](#)

© Copyright 2005 IEEE -

Indexed by
 Inspec

[Home](#) | [Login](#) | [Logout](#) | [Access Information](#) | [Alerts](#) |

Welcome United States Patent and Trademark Office

[Search Results](#)[BROWSE](#)[SEARCH](#)[IEEE XPLORE GUIDE](#)

Results for "(copper doped aluminum<in>metadata) <and> (pad<in>metadata)"



Your search matched 0 of 1189536 documents.

A maximum of 100 results are displayed, 25 to a page, sorted by Relevance in Descending order.

[» View Session History](#)[» New Search](#)[» Key](#)

IEEE JNL IEEE Journal or Magazine

IEE JNL IEE Journal or Magazine

IEEE CNF IEEE Conference Proceeding

IEE CNF IEE Conference Proceeding

IEEE STD IEEE Standard

Modify Search

☐ Check to search only within this results setDisplay Format: ☒ Citation ☐ Citation & Abstract

No results were found.

Please edit your search criteria and try again. Refer to the Help pages if you need assistance revisir

[Help](#) [Contact Us](#) [Privacy & :](#)

© Copyright 2005 IEEE -

indexed by


[Home](#) | [Login](#) | [Logout](#) | [Access Information](#) | [Alerts](#) |

Welcome United States Patent and Trademark Office

Search Results**BROWSE****SEARCH****IEEE XPLORE GUIDE**

Results for "((copper<in>metadata) <and> (oxide<in>metadata) <and> (aluminum<in>g..."

Your search matched 4 of 73 documents.

A maximum of 100 results are displayed, 25 to a page, sorted by Relevance in Descending order.

Print

» [View Session History](#)» [New Search](#)» **Key**

IEEE JNL IEEE Journal or Magazine

IEEE JNL IEE Journal or Magazine

IEEE CNF IEEE Conference Proceeding

IEEE CNF IEE Conference Proceeding

IEEE STD IEEE Standard

Modify Search

((copper<in>metadata) <and> (oxide<in>metadata) <and> (aluminum<in>metada

☐ Check to search only within this results set**Display Format:** ☒ Citation ☐ Citation & Abstract**Select Article Information**

- ☐ 1. **Corrosion susceptibility of thin-film metallizations**
Griffin, A.J., Jr.; Brotzen, F.R.; McPherson, J.W.; Dunn, C.F.;
Reliability Physics Symposium 1992. 30th Annual Proceedings., International
31 March-2 April 1992 Page(s):239 - 246
[AbstractPlus](#) | [Full Text: PDF\(712 KB\)](#) IEEE CNF
- ☐ 2. **Corrosion susceptibility of Al-Cu and Al-Cu-Si films**
Lawrence, J.D.; McPherson, J.W.;
Reliability Physics Symposium, 1991, 29th Annual Proceedings., International
9-11 April 1991 Page(s):102 - 106
[AbstractPlus](#) | [Full Text: PDF\(432 KB\)](#) IEEE CNF
- ☐ 3. **Corrosion behaviour of thin-film metallizations on CVD W and sputtered W-Ti**
Griffin, A.J., Jr.; Hernandez, S.E.; Brotzen, F.R.; Lawrence, J.D.; McPherson, J.W.; Du
Reliability Physics Symposium, 1993. 31st Annual Proceedings., International
23-25 March 1993 Page(s):327 - 333
[AbstractPlus](#) | [Full Text: PDF\(600 KB\)](#) IEEE CNF
- ☐ 4. **Break through developments in electroless nickel/gold plating on copper based :**
Strandjord, A.J.G.; Popelar, S.F.; Erickson, C.A.;
Advanced Packaging Materials: Processes, Properties and Interfaces, 2000. Proceedin
Symposium on
6-8 March 2000 Page(s):107 - 111
[AbstractPlus](#) | [Full Text: PDF\(512 KB\)](#) IEEE CNF

[View Selected Items](#)
 Indexed by
 Inspec
[Help](#) · [Contact Us](#) · [Privacy &](#)

© Copyright 2005 IEEE -